Display Elektronik GmbH

DATA SHEET

TFT MODULE

DEM 412960A VMH-PW-N

3,4" TFT

Product Specification

Ver.: 2

Revision History

Revision	Date	Originator	Detail	Remarks
0	10.07.2023	LQ	Initial Release	-
1	11.07.2023	LQ	Modify Description of DB0DB23	P10
			Add Weight	P4
2	07.08.2023	LL	Add DC Characteristics	P5
			Add Chromacity Transmissive	P6

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, Driver ICs and a Backlight Unit.

2. Module Parameter

Features	Details	Unit
Display Size (Diagonal)	3.4"	-
LCD Type	IPS TFT	-
Display Mode	Transmissive / Normally Black	-
Resolution	412 x RGB x 960	Pixels
View Direction	Full Viewing	Best Image
Module Outline	38.135 x 87.82 x 2.55 (Note1)	mm
Active Area	33.99 x 79.20	mm
Pixel Size	82.50 x 82.50	mm
Pixel Arrangement	RGB Vertical Stripe	-
Display Colors	16.7 Million	-
Interface	3-Wire-SPI + 24-Bit-RGB	-
Driver IC	ST7701SN-G5 (Sitronix)	-
With or Without Touch Panel	Without	-
Operating Temperature	-20°C to +70°C	°C
Storage Temperature	-30°C to +80°C	°C
Weight	~ 18	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

GND=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VCC	-0.3	4.6	V
Storage Temperature	Tstg	-30	+80	°С
Operating Temperature	Тор	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over +50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit
Analog Operating Voltage	VCC	2.5	2.8	3.3	V
Logic Low Input Voltage	VIL	GND	-	0.3*VDD	V
Logic High Input Voltage	ViH	0.7*VDD	-	VDD	V
Logic Low Output Voltage	Vol	GND	-	0.2*VDD	V
Logic High Output Voltage	Voh	0.8*VDD	-	VDD	V
Current Consumption All White	Icc	-	25.8	-	mA

5. Backlight Characteristic

5.1. Backlight Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	Ta=25 °C, IF=20mA/LED	17.4	19.2	20.4	V
Forward Current	lF	Ta=25 °C, VF=3.2V/LED	-	20	-	mA
Power Dissipation	Pd		-	384	-	mW
Uniformity	Avg		-	80	-	%
LED Lifetime (25°C)	-		20000	30000	-	Hrs
Drive Method	Constant current					
LED Configuration		6 White LEDs (6	LEDs in	string)		

Note1: LED lifetime defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25°C \pm 2°C, 60%RH \pm 5%, I_F=20mA/LED.

5.2. Backlighting Circuit



6. Optical Characteristics

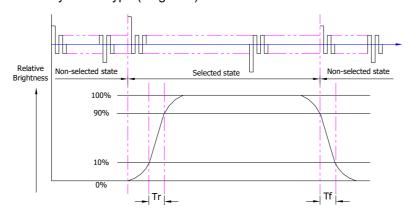
6.1. Optical Characteristics

Ta=25°C, VCC=2.8V

	Item		Symbol	Condition	S	Unit		
			Syllibol	Condition	Min.	Тур.	Max.	Offic
	Luminance On							
<u> </u>	TFT(I_f =20	mA/LED)	Lv	Normally	248	310	-	cd/m²
ode	Contrast Rat	io(See 6.3)	CR	viewing angle	-	1000	-	
Backlight On (Transmissive Mode)	Response Time (See 6.2)		TR+TF	$\theta x = \phi Y = 0^{\circ}$	-	30	35	ms
nis		Dod	XR		0.588	0.638	0.688	0.588
nsr		Red	YR		0.307	0.357	0.407	0.307
Tra	Chua na atia itu	ve -	Xg		0.254	0.304	0.354	0.254
) u	Chromaticity Transmissive		Yg		0.585	0.635	0.685	0.585
ot C	(See 6.5)		Хв		0.099	0.149	0.199	0.099
	(000 0.5)		YB		0.082	0.132	0.182	0.082
ack		White	Xw		0.262	0.312	0.362	0.262
æ		vviile	Yw		0.315	0.365	0.415	0.315
	Viewing	Horizontal	θx+		ı	85	ı	
	Viewing	Tionzoniai	θx-	Center CR≥10	-	85	-	Dog
	Angle (See 6.4)	Vertical	φY+	Center CR210	1	85	-	Deg.
	(000 0.4)	Vertical	φY-		-	85	-	
	NTSC Ratio	o(Gamut)			50	60	-	%

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

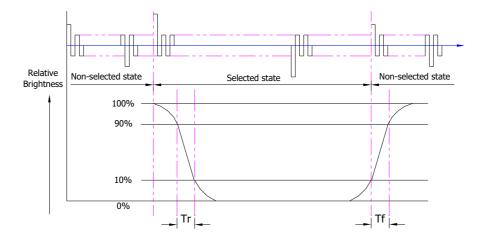


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

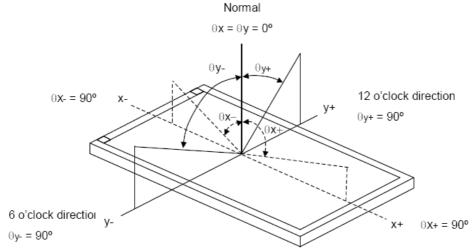
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test Pattern	A: All Pixels white
rest Pattern	B: All Pixel black
Contrast Setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles

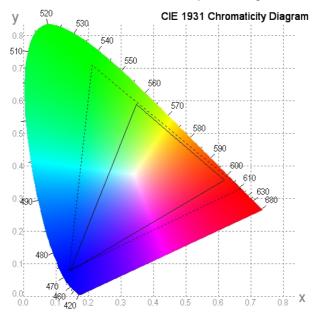


Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

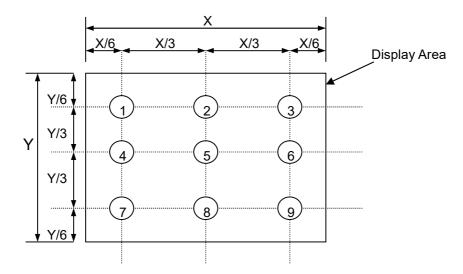


6.6. Definition of Surface Luminance, Uniformity and Transmittance

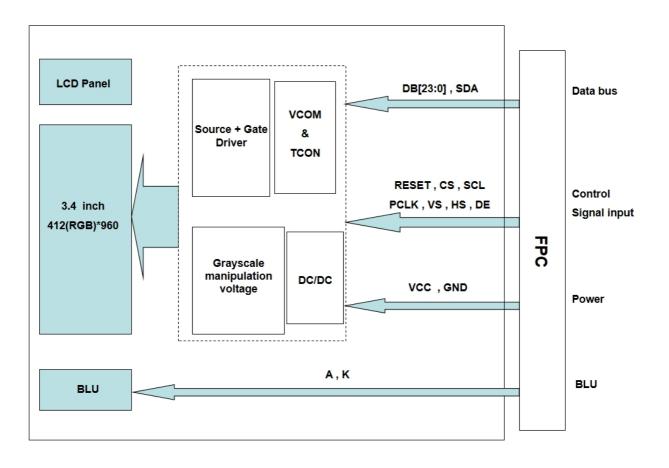
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance: L_V = average (L_{P1} : L_{P9})
- 6.6.2. Uniformity = Minimal $(L_{P1}:L_{P9})$ / Maximal $(L_{P1}:L_{P9})$ * 100%
- 6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply

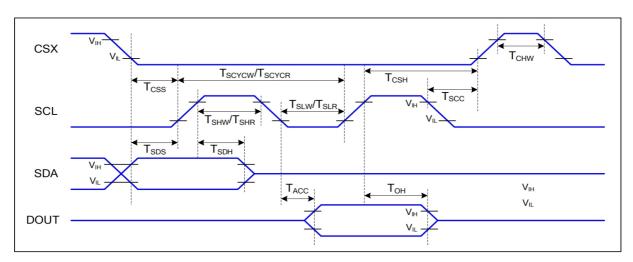


8. Interface Pins Definition

No.	Symbol	Function
1	LED_K	Backlight Cathode
2	LED_A	Backlight Anode
3	RESET	RESET
4	VCC	Power source
5	CS	Chip select signal
6	SCL	Serial clock input for SPI interface
7	SDA	Serial data input pin for SPI Interface
8	GND	Ground
9	PCLK	Clock signal to sample each data
10	GND	Ground
11	VS	Vertical synchronizing signal
12	HS	Horizontal synchronizing signal
13	DE	Input data enable control
14	GND	Ground
15	DB0	R0 Data signal (LSB).
16	DB1	R1 Data signal
17	DB2	R2 Data signal
18	DB3	R3 Data signal
19	DB4	R4 Data signal
20	DB5	R5 Data signal
21	DB6	R6 Data signal
22	DB7	R7 Data signal (MSB)
23	DB8	G0 Data signal (LSB).
24	DB9	G1 Data signal
25	DB10	G2 Data signal
26	DB11	G3 Data signal
27	DB12	G4 Data signal
28	DB13	G5 Data signal
29	DB14	G6 Data signal
30	DB15	G7 Data signal (MSB).
31	DB16	B0 Data signal (LSB).
32	DB17	B1 Data signal
33	DB18	B2 Data signal
34	DB19	B3 Data signal
35	DB20	B4 Data signal
36	DB21	B5 Data signal
37	DB22	B6 Data signal
38	DB23	B7 Data signal (MSB).
39	GND	Ground
40	GND	Ground

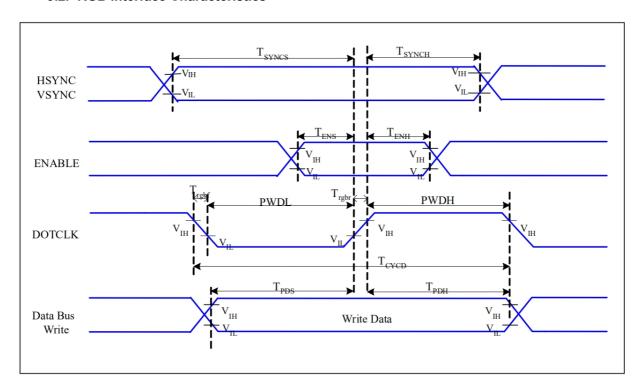
9. AC Characteristics

9.1. 3-line Serial Interface Characteristics



Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setup time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	Tcss	Chip select setup time (read)	60		ns	
	Tscc	Chip select hold time (read)	60		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
SCL	Tslw	SCL "L" pulse width (Write)	15		ns	
SCL	Tscycr	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
SDO	T _{ACC}	Access time	20	50	ns	Max: CL=30pF
(DOUT)	Тон	Output disable time	50	50	ns	Min: CL=8pF

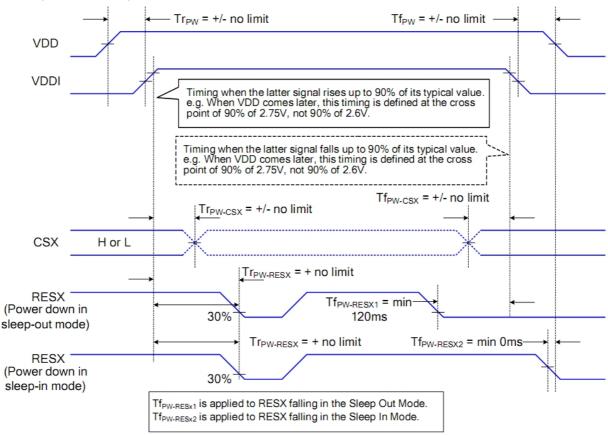
9.2. RGB Interface Characteristics



Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC,	+	VSYNC, HSYNC Setup Time	5			
VSYNC	T _{SYNCS}	VSTNC, HSTNC Setup Time	5	-	ns	
ENABLE	T _{ENS}	Enable Setup Time	5	-	ns	
ENABLE	T_{ENH}	Enable Hold Time	5	-	ns	
	PWDH	DOTCLK High-level Pulse Width	15	-	ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	15	-	ns	
DOTCLK	T _{CYCD}	DOTCLK Cycle Time	33	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	15	ns	
D.D.	T _{PDS}	PD Data Setup Time	5	-	ns	
DB	T_{PDH}	PD Data Hold Time	5	-	ns	

9.3. Power ON/OFF Sequence

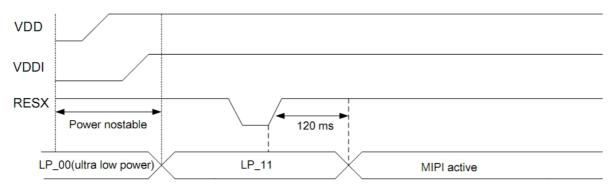
The power on/off sequence is illustrated below



Notes:

- 1. There will be no damage to the ST7701SN if the power sequences are not met.
- 2. There will be no abnormal visible effects on the display panel during the Power On/Off Sequences.
- 3. There will be no abnormal visible effects on the display between the end of Power On Sequence and before receiving the Sleep Out command, and also between receiving the Sleep In command and the Power Off Sequence.
- 4. If the RESX line is not steadily held by the host during the Power On Sequence as defined in Sections 9.3.1, then it will be necessary to apply the Hardware Reset (RESX) after the completion of the Host Power On Sequence to ensure correct operations. Otherwise, all the functions are not guaranteed.
- 5. When VDDA is in power off State, the MIPI must set in Ultra Low Power Mode (GND Level).

Note5:



9.3.1. Uncontrolled Power Off

The uncontrolled power-off means a situation which removed a battery without the controlled power off sequence. It will neither damage the module or the host interface.

If uncontrolled power-off happened, the display will go blank and there will not any visible effect on the display (blank display) and remains blank until "Power On Sequence" powers it up.

10. Quality Assurance

10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2. Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5.

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3. Nonconforming Analysis & Disposition

- 10.3.1. Nonconforming analysis:
 - 10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
 - 10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
 - 10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.
- 10.3.2. Disposition of nonconforming:
 - 10.3.2.1. Non-conforming product over PPM level will be replaced.
 - 10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

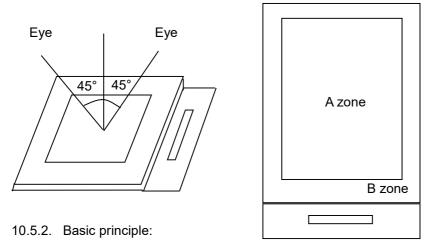
10.4. Agreement Items

Shall negotiate with customer if the following situation occurs:

- 10.4.1. There is any discrepancy in standard of quality assurance.
- 10.4.2. Additional requirement to be added in product specification.
- 10.4.3. Any other special problem.

10.5. Standard of the Product Visual Inspection

- 10.5.1. Appearance inspection:
 - 10.5.1.1. The inspection must be under illumination about $1000 1500 \, lx$, and the distance of view must be at $30 \, cm \pm 2 \, cm$.
 - 10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.
 - 10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.10.5.2.2. New item must be added on time when it is necessary.

10.6.Inspection Specification

No.	Item	Criteria (Unit: mm)				
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	φ= (a + b) /2 Distance between 2 defects sho	Area Size φ≤0.10 0.10<φ≤0.15 0.15<φ≤0.25 0.25<φ Total	Acc. Qty Ignore 2 1 0 2 no include φ≤ 0.10		
02	Electrical Defect (Minor defect)	Display Ar Bright dot 0 Dark dot N≤2 Total dot N≤2 Mura Not visible Remark: 1. Bright dot caused by scrate	0 N≤2 N≤2 e through 5% ND filters.			

03		Length	Length Width Acc. Qty			
		/	W ≦ 0.03	Ignore		
		L ≦ 2.5	$0.03 < W \le 0.05$	3		
		L ≦ 2.5	$0.05 < W \le 0.10$	2		
		/	0.1 < W	0		
		Total 3				
		Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.				
04	Glass Crack (Minor defect)	Crack is potential to enlarge, any type is not allowed.				

	Glass Chipping Pad Area: (Minor defect)				
05	(Willion defect)	Length and Width Acc. Qty	Acc. Qty		
		c > 3.0, b< 1.0			
		c< 3.0, b< 1.0 3			
		a <glass td="" thickness<=""></glass>			
	b a c		•		
	Glass Chipping Rear of Pad Area: (Minor defect)				
		Length and Width Acc. Qty			
		c > 3.0, b< 1.0			
06		c< 3.0, b< 1.0 2			
		c< 3.0, b< 0.5 4			
	b c	a <glass td="" thickness<=""></glass>			
	Glass Chipping Except Pad Area: (Minor defect)				
		Length and Width Acc. Qty			
		c > 3.0, b< 1.0 1			
07		c< 3.0, b< 1.0 2			
		c< 3.0, b< 0.5 4			
	a	a <glass td="" thickness<=""><td></td></glass>			
	Glass Corner Chipping:				
	(Minor defect)		1		
08		Length and Width Acc. Qty			
		c < 3.0, b< 3.0 Ignore			
	base	a <glass td="" thickness<=""><td></td></glass>			

	Class Dur					
	Glass Burr:					
	(Minor defect)				a.4la	A = = = = = = = = = = = = = = = = = = =
				Len	_	Acc. Qty
				F <	1.0	Ignore
09	F					
			Glass burr don't affect assemble and module dimension.			
	FPC Defect: (Minor defect)		40.4 Death wind also will be a said.			
	a→∷<	_	10.1 Dent, pinhole width a <w 3.<="" td=""></w>			
10	$w \rightarrow \bigcirc$		(w: circuitry width.)			
			10.2 Open circuit is unacceptable.			
			10.3 N	lo oxidation,	contaminat	ion and distortion.
			Dia	meter	Acc. Q	tv
				0.20	Ignore	
11	Bubble on Polarizer			<φ≤0.30	4	
	(Minor defect)	 		<φ≤0.50	1	
				i0 < φ	None	•
			0.0	Ψ - Ψ	INOTIC	,
12			Dia	meter	Acc. Q	ty
	Dent on Polarizer			0.20	Ignore	
	(Minor defect)			<φ≤0.30	4	
					1	
				0 < φ	None	!
13	Bezel	13.1 No rust, distort				
		13.2 No visible finge	erprints,	stains or oth	ner contami	nation.

14	РСВ	14.1 No distortion or contamination on PCB terminals. 14.2 All components on PCB must same as documented on the BOM/component layout. 14.3 Follow IPC-A-600F.	
15	Soldering	Follow IPC-A-610C standard	
16	Electrical Defect (Major defect)	The below defects must be rejected. 16.1 Missing vertical / horizontal segment, 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch Panel no function.	

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

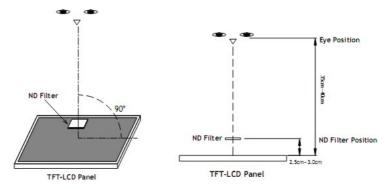
10.8.Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

10.9. Packing

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area

11. Reliability Specification

No	ltem	Condition	Quantity	Criteria
1	High Temperature Operating	+70°C, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	+50°C, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	+80°C, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-20°C, 60min~+70°C, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity: 5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Floatrical Static Discharge	Air: \pm 4kV 150pF/330 Ω 5 times	2	GB/T17626.2
	Electrical Static Discharge	Contact: ± 2 kV 150pF/330 Ω 5 times		-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value.

12. Precautions and Warranty

12.1. Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2. Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

12.4. Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

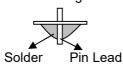
Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

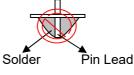
Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



Recommended



Not Recommended

12.4.2. Pins of EL

- 12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.
- 12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.
- 12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

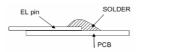
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting



EL pin SOLDER PCB

Recommended

Not Recommended

12.4.2.7. The type of the solder iron:





Recommended

Not Recommended

12.4.2.8. Solder Pad



12.5. Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

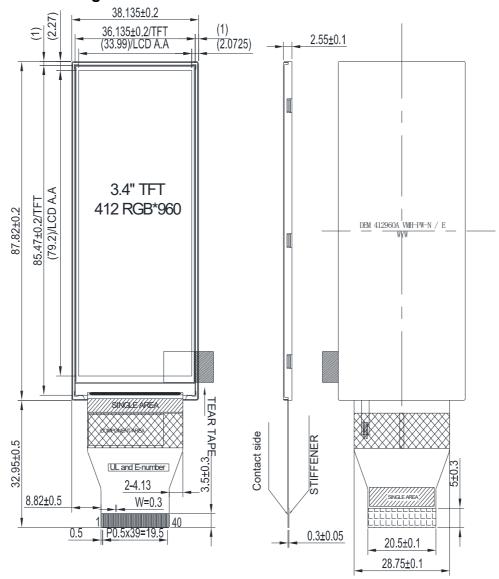
12.6. Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7. Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Outline Drawing





NOTES:

- 1.Display Size: 3.4" TFT
- 2. Viewing Direction: Full View
- 4. Display Mode: Transmissive / Normal Black
- 5. Operation Temperature: -20°C to +70°C
- 6.Storage Temperature: -30°C to +80°C
- 7. Driver IC: ST7701SN-G5 (Sitronix)
- 7. Power Supply Voltage: 2.8 Volt (typ.)
- 8.Backlight: White / 19.2Volt / 20mA (typ.)
- 9. Brighness: 310cd/m² (typ.)
- 10.ROHS must be complied
- * Unspecification Tolerance are $\pm\,0.2$ mm

1	LED K	21	DB6
2	LED_A	22	DB7
3	RESET	23	DB8
4	VCC	24	DB9
5	CS	25	DB10
6	SCL	26	DB11
7	SDA	27	DB12
8	GND	28	DB13
9	PCLK	29	DB14
10	GND	30	DB15
11	VS	31	DB16
12	HS	32	DB17
13	DE	33	DB18
14	GND	34	DB19
15	DB0	35	DB20
16	DB1	36	DB21
17	DB2	37	DB22
18	DB3	38	DB23
19	DB4	39	GND
20	DB5	40	GND